



**FOR IMMEDIATE RELEASE**

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**ASE INC. PRESS RELEASE:  
ACHIEVEMENT OF THE MINIMUM ACQUISITION AMOUNT AND  
SATISFACTION OF THE CONDITION TO THE USI TENDER OFFER**

Taipei, Taiwan, R.O.C., June 23<sup>rd</sup>, 2010 - Advanced Semiconductor Engineering, Inc. (TAIEX: 2311, NYSE: ASX) (hereinafter "ASE", or the "Company") launched the tender offer to acquire the common shares of Universal Scientific Industrial Co., Ltd. ("USI"). The number of common shares of USI tendered by the shareholders has exceeded 54,422,636 on June 22<sup>nd</sup>, 2010. Therefore, the condition to the tender offer has been satisfied.

ASE plans to conduct the tender offer until 3:30pm on August 5<sup>th</sup>, 2010.

**Safe Harbor Notice**

This press release contains "forward-looking statements" within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended, including statements regarding our future results of operations and business prospects. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to be reliable, you should not place undue reliance on these forward-looking statements, which apply only as of the date of this presentation. The words "anticipate", "believe", "estimate", "expect", "intend", "plan" and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this presentation. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclical and market conditions in the semiconductor industry; demand for the outsourced semiconductor packaging and testing services we offer and for such outsourced services generally; the highly competitive semiconductor industry; our ability to introduce new packaging, interconnect materials and testing technologies in order to remain competitive; our ability to successfully integrate pending and future mergers and acquisitions; international business activities; our business strategy; general economic and political conditions, including the recent global financial crisis; possible disruptions in commercial activities caused by natural or human-induced disasters; our future expansion plans and capital expenditures; the strained relationship between the Republic of China and the People's Republic of China; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2009 Annual Report on Form 20-F filed on June 11, 2010.